

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.05998	6.5	0.052
	Doped Silicon	Silicon (Si)	7440-21-3	0.92283	100.0	0.8
Subtotal				0.98281	106.5	0.852
Clip Frame	Copper alloy	Phosphorous (P)	7723-14-0	0	0.04	0
	Copper alloy	Iron (Fe)	7439-89-6	0	0.1	0
	Copper alloy	Copper (Cu)	7440-50-8	0	99.86	0
Subtotal				0	100	0
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.04614	5.0	0.04
	Lead alloy	Silver (Ag)	7440-22-4	0.02307	2.5	0.02
	Lead alloy	Lead (Pb)	7439-92-1	0.85362	92.5	0.74
Subtotal				0.92283	100	0.8
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.12135	8.0	3.5728
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.53349	8.8	3.93008
	Filler	Silica fused	60676-86-0	42.75903	83.0	37.0678
	Carbon Black	Carbon black	1333-86-4	0.10303	0.2	0.08932
Subtotal				51.5169	100	44.66
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01823	0.04	0.0158
	Copper alloy	Iron (Fe)	7439-89-6	0.04556	0.1	0.0395
	Copper alloy	Copper (Cu)	7440-50-8	45.50087	99.86	39.4447
Subtotal				45.56466	100	39.5
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.07279	100.0	0.93
Subtotal				1.07279	100	0.93
Total				100.05999	100	86.742

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